L Number	Hits		DB	Time stamp
1	2	("6138349").PN.	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 17:53
2	24	("4158190" "4321589" "4759069" "4785474" "4888226" "4956866" "5041976" "5060279" "5193513" "5213864" "5235329" "5274913" "5275841" "5287411" "5307060" "5365403" "5422543" "5483936" "5526234" "5559508" "5568684" "5644103" "5663869" "5710555").PN.	USPAT	2004/03/10 17:52
3	135	361/\$.ccls. and (conformal adj coating)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 17:54
5	0	((361/\$.ccls. and (conformal adj coating)) and (IC or chip or die or device)) and windown	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 17:54
4	104	(361/\$.ccls. and (conformal adj coating)) and (IC or chip or die or device)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 18:34
6	4	("3484536" "3652333" "3653959" "3669733").PN.	USPAT	2004/03/10 18:23
7	6	4300184.URPN.	USPAT	2004/03/10 18:23
8	22	4047198.URPN.	USPAT	2004/03/10 18:25
9	64	(conformal adj coating) with (windown or cavity or opening or recess)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 18:28
10	33	((conformal adj coating) with (windown or cavity or opening or recess)) and @pd<19971218	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 18:29
11	2	5690759.URPN.	USPAT	2004/03/10 18:34
12	407757	coating and (IC or chip or die or device)	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 18:34
13	278848	(coating and (IC or chip or die or device)) and @pd<19971218	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 18:35
14	15	((coating and (IC or chip or die or device)) and @pd<19971218) and windown	USPAT; EPO; JPO; DERWENT; USOCR	2004/03/10 18:35